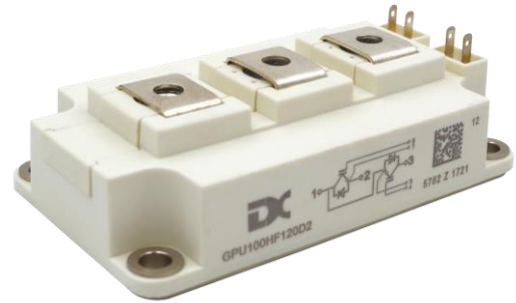


1200V/200A 2 in one-package

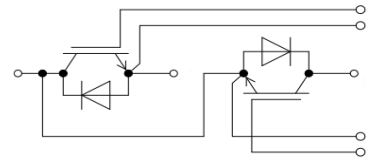
Features:

- 1200V200A, VCE(sat)(typ.)=3.0V
- Ultrafast switching speed
- Excellent short circuit ruggedness
- 62mm half bridge module



General Applications:

Daxin's IGBTs offer ultrafast switching speed for application such as welding, inductive heating, UPS and other high frequency applications



Equivalent Circuit Schematic

Absolute Maximum Ratings of IGBT

V _{CES}	Collector to Emitter Voltage		1200	V
V _{GES}	Continuous Gate to Emitter Voltage		±30	V
I _C	Continuous Collector Current	T _C = 25°C	400	A
		T _C = 100°C	200	
I _{CM}	Pulse Collector Current	T _J = 150°C	400	A
P _D	Maximum Power Dissipation (IGBT)	T _C = 25°C, T _J = 150°C	860	W
t _{sc}	Short Circuit Withstand Time		> 10	μs
T _J	Maximum IGBT Junction Temperature		150	°C
T _{JOP}	Maximum Operating Junction Temperature Range		-40 to +150	°C
T _{stg}	Storage Temperature Range		-40 to +125	°C

Absolute Maximum Ratings of Freewheeling Diode

V _{RRM}	Repetitive Peak Reverse Voltage Preliminary Data		1200	V
I _F	Diode Continuous Forward Current	T _C = 25°C	400	A
		T _C = 100°C	200	
I _{FM}	Diode Maximum Forward Current		400	A

Electrical Characteristics of IGBT at $T_J = 25^\circ\text{C}$ (Unless Otherwise Specified)

Parameter		Test Conditions		Min	Typ	Max	Unit
BV _{CES}	Collector to Emitter Breakdown Voltage	V _{GE} = 0V, I _C = 1mA		1200			V
I _{CES}	Collector to Emitter Leakage Current	V _{GE} = 0V, V _{CE} = V _{CES}				5	mA
I _{GES}	Gate to Emitter Leakage Current	V _{GE} = ±30V, V _{CE} = 0V				400	nA
V _{GE(th)}	Gate Threshold Voltage	I _C = 1mA, V _{CE} = V _{GE}		4.5		5.7	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage (Module Level)	I _C = 200A, V _{GE} = 15V	T _J = 25°C		3.00	3.20	V
			T _J = 125°C		3.60		

Switching Characteristics of IGBT

$t_{d(on)}$	Turn-on Delay Time	$V_{CC} = 600V$ $I_C = 200A$ $R_G = 4.7\Omega$ $V_{GE} = \pm 15V$ Inductive Load	$T_J = 25^{\circ}C$		90		ns
			$T_J = 125^{\circ}C$		95		
t_r	Turn-on Rise Time		$T_J = 25^{\circ}C$		85		ns
			$T_J = 125^{\circ}C$		90		
$t_{d(off)}$	Turn-off Delay Time		$T_J = 25^{\circ}C$		670		ns
			$T_J = 125^{\circ}C$		725		
t_f	Turn-off Fall Time		$T_J = 25^{\circ}C$		110		ns
			$T_J = 125^{\circ}C$		130		
E_{on}	Turn-on Switching Loss		$T_J = 25^{\circ}C$		8.5		mJ
			$T_J = 125^{\circ}C$		10.5		
E_{off}	Turn-off Switching Loss		$T_J = 25^{\circ}C$		11.0		mJ
			$T_J = 125^{\circ}C$		14.0		
Q_g	Total Gate Charge		$T_J = 25^{\circ}C$		1740		nC
R_{gint}	Integrated gate resistor	$f = 1M;$ $V_{pp} = 1V$	$T_J = 25^{\circ}C$		2.5		Ω
C_{ies}	Input Capacitance	$V_{CE} = 25V$ $V_{GE} = 0V$ $f = 1MHz$	$T_J = 25^{\circ}C$		17.5		nF
C_{oes}	Output Capacitance		$T_J = 25^{\circ}C$		2.4		
C_{res}	Reverse Transfer Capacitance		$T_J = 25^{\circ}C$		1.4		
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (IGBT)					0.145	$^{\circ}C/W$

Electrical and Switching Characteristics of Freewheeling Diode

V _F	Diode Forward Voltage	I _F = 200A , V _{GE} = 0V	T _J = 25°C		1.90	2.20	V
			T _J = 125°C		1.90		
t _{rr}	Diode Reverse Recovery Time	I _F = 200A, di/dt=2600A/μs, V _{rr} = 600V,	T _J = 25°C		160		ns
			T _J = 125°C		220		
I _{rr}	Diode Peak Reverse Recovery Current		T _J = 25°C		170		A
			T _J = 125°C		210		
Q _{rr}	Diode Reverse Recovery Charge		T _J = 25°C		16.50		nC
			T _J = 125°C		26.50		
E _{rr}	Diode Reverse Recovery Energy		T _J = 25°C		5.50		mJ
			T _J = 125°C		9.00		
R _{θJC}	Thermal Resistance, Junction-to-Case (Diode)					0.157	°C/W

Module Characteristics

Parameter		Min.	Typ.	Max.	Unit
V_{iso}	Isolation Voltage (All Terminals Shorted), $f = 50Hz$, 1minute	2500			V
$R_{\theta CS}$	Case-To-Sink(Conductive Grease Applied)		0.1		$^{\circ}C/W$
M	Power Terminals Screw: M6	3.0		5.0	N·m
M	Mounting Screw: M6	4.0		6.0	N·m
G	Weight		315		g

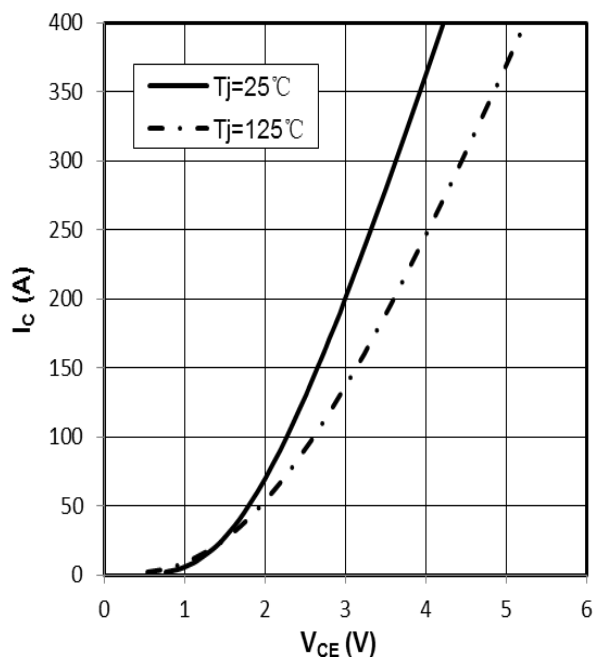


Fig 1. output characteristic IGBT,
 $I_c=f(V_{ce}), V_{GE}=15V$

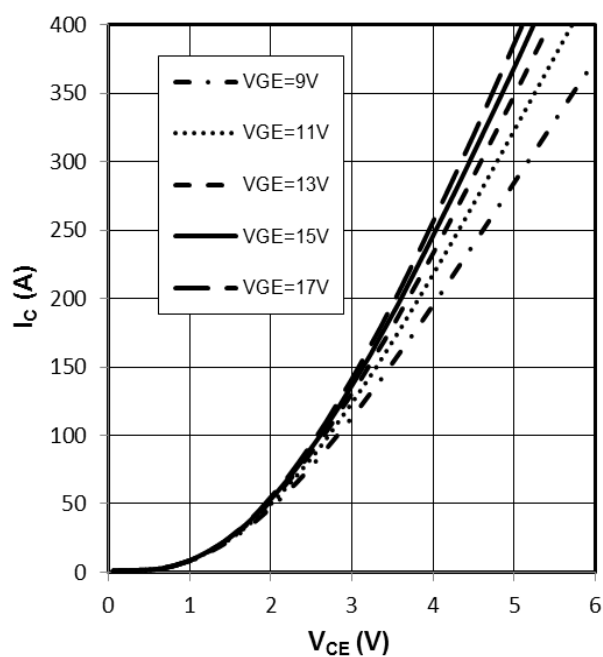


Fig 2. output characteristic IGBT,
 $I_c=f(V_{ce}), T_j=125^\circ C$

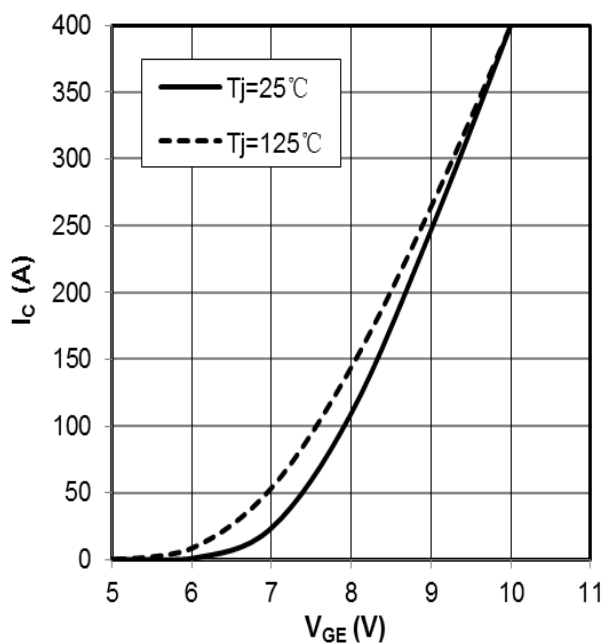


Fig 3. transfer characteristic IGBT,
 $I_c=f(V_{GE}), V_{ce}=20V$

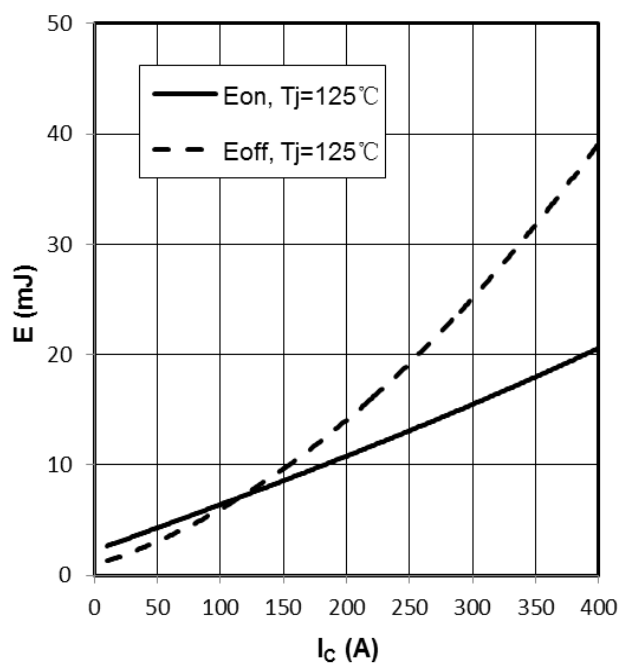


Fig 4. switching losses IGBT, $E_{on}=f(I_c), E_{off}=f(I_c)$,
 $V_{GE}=\pm 15V, R_{Gon}=4.7\Omega, R_{GoFF}=4.7\Omega, V_{ce}=600V$

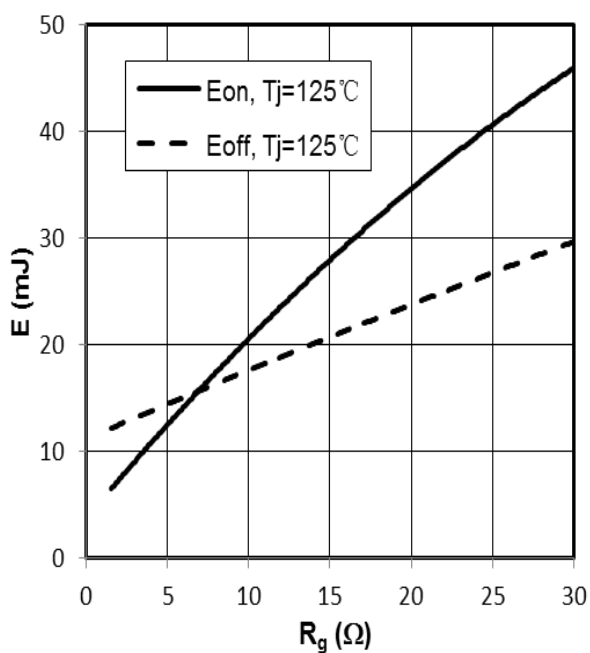


Fig 5. switching losses IGBT, $E_{on}=f(R_g)$, $E_{off}=f(R_g)$, $V_{GE}=\pm 15V$, $I_c=200A$, $V_{CE}=600V$

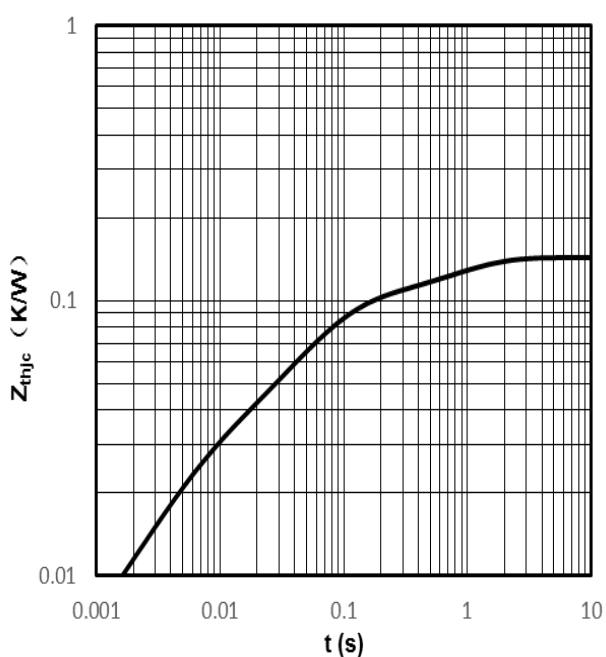


Fig 6. transient thermal impedance IGBT, $Z_{thjc}=f(t)$

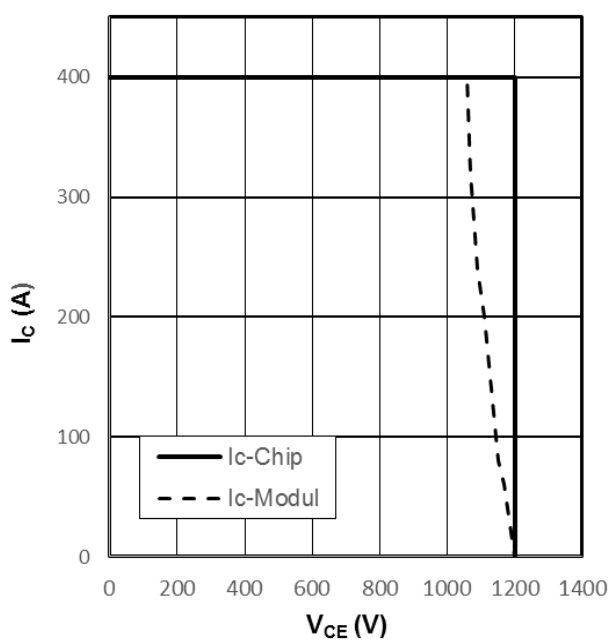


Fig 7. reverse bias safe operating area IGBT, $I_c=f(V_{CE})$, $V_{GE}=\pm 15V$, $R_{GoFF}=4.7\Omega$, $T_j=125^\circ C$

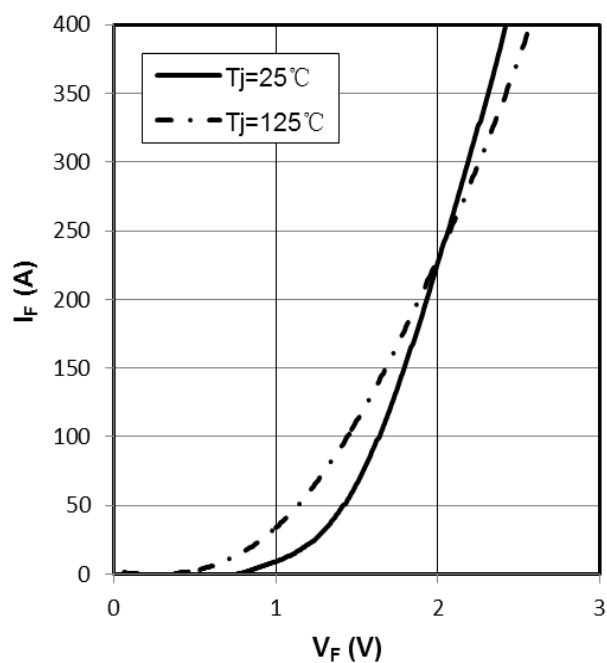


Fig 8. forward characteristic of Diode, $I_F=f(V_F)$

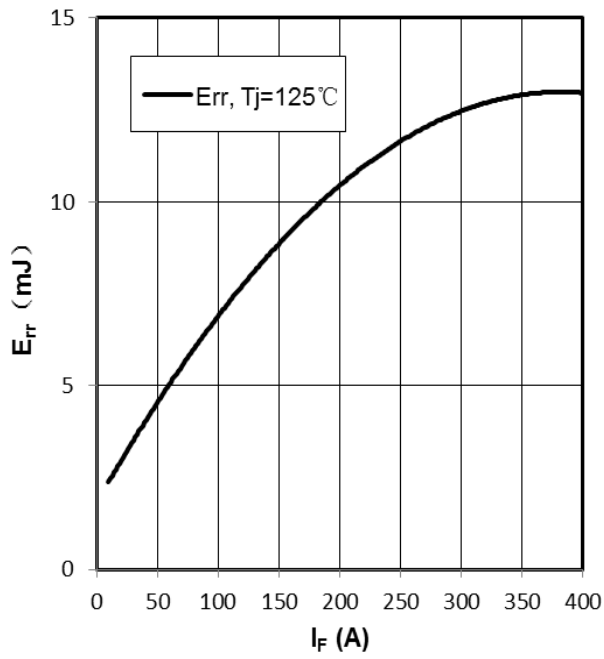


Fig 9. switching losses Diode,
 $E_{rr}=f(I_F)$, $R_{Gon}=4.7\Omega$, $V_{CE}=600V$

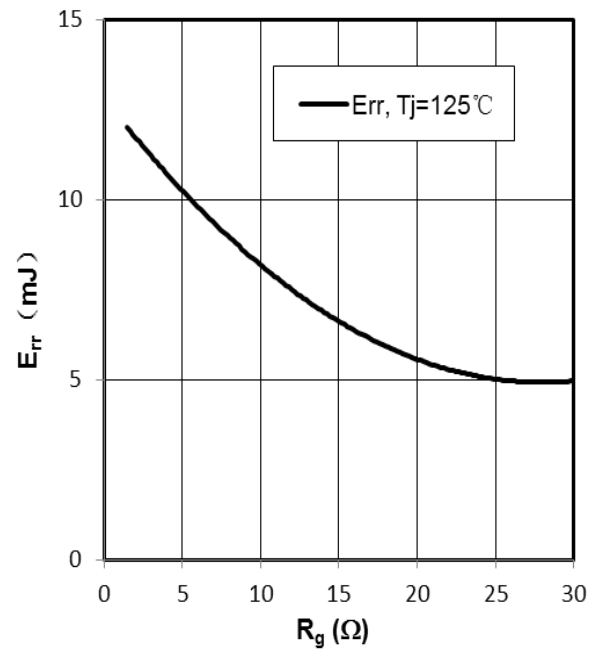
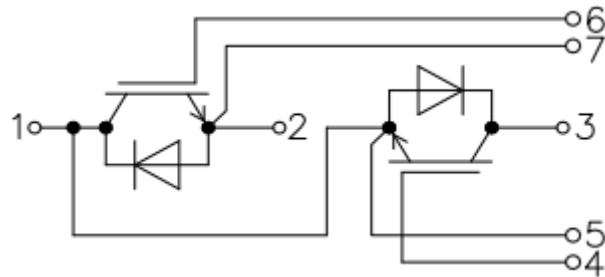


Fig 10. switching losses Diode,
 $E_{rr}=f(R_g)$, $I_F=200A$, $V_{CE}=600V$

Internal Circuit:



Package Dimension
Dimensions in Millimeters

